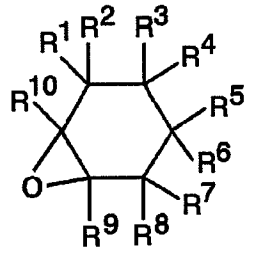
AMENDED CLAIM SET:

1. (withdrawn - currently amended) A heat-curable resin composition comprising an alicyclic epoxy compound (a) having a structure represented by the following general formula (1),

General formula (1)

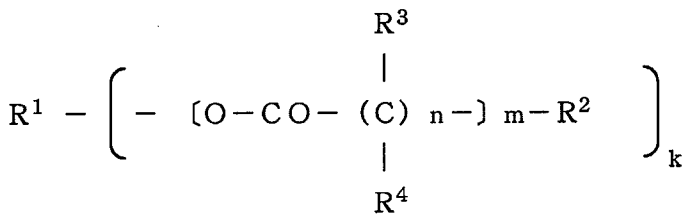


[[[In]] wherein, in the general formula (1): R^1 to R^{10} each represent hydrogen, or a saturated or unsaturated hydrocarbon group having 1 to 20 carbon atoms, wherein [[(]] an ether bond, an ester bond, or an alcoholic hydroxyl group may be included in the hydrocarbon group[[)]]; R^1 to R^{10} may each represent a residue derived by removing any one of R^1 to R^{10} from the structure represented by the general formula (1), or a residue derived by removing hydrogen from any one of R^1 to R^{10}; and the phrase "in the hydrocarbon group" refers to "inside the hydrocarbon group", "at terminals of the hydrocarbon group", or "within bonds of the hydrocarbon group"[[]], a cationic polymerization initiator (i), and ~~optionally~~ a surfactant (e), wherein the surfactant (e) comprises a silicon-based surfactant (e1) having a dimethylsiloxane skeleton and/or a fluorine-based surfactant (e2) having hydrophobic groups of a hydrocarbon-based surfactant entirely or partially substituted with fluorine atoms.

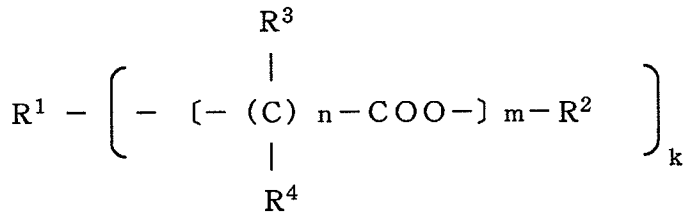
2. (withdrawn) A heat-curable resin composition according to claim 1, further comprising a polyol (b) having two or more hydroxyl groups on terminals.

3. (currently amended) A heat-curable resin composition comprising an alicyclic epoxy compound (a') having a structure represented by the following general formula (2),

General formula (2)

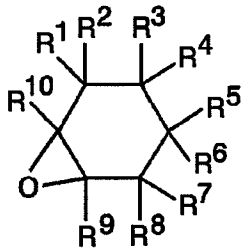


or



[[[In]] wherein, in the general formula (2): R^1 represents hydrogen, or a hydrocarbon group of a valence k having 1 to 20 carbon atoms, wherein [[(]] an ether bond, an ester bond, or an alcoholic hydroxyl group may be included in the hydrocarbon group[[)]]; R^2 represents hydrogen, a hydroxyl group, or a hydrocarbon group having 1 to 20 carbon atoms, wherein [[(]] an ether bond, an ester bond, or an alcoholic hydroxyl group may be included in the hydrocarbon group[[)]]; at least one of R^1 and R^2 represents ~~may represent~~ a residue derived by removing any one of R^1 to R^{10} from the structure represented by the following general formula (1); R^3 and R^4 each represents hydrogen, or a hydrocarbon group having 1 to 20 carbon atoms; a plurality of R^3s and R^4s may be the same or different from each other; "n" represents an integer of 3 to 10; "m" represents an integer of 2 to 10; "k" represents an integer of 1 to 10; when "k" is 2 or more, "k" pieces of group structures (that is, "k" represents an integer of 2 to 10; "k" represents an integer of 1 to 10; when "k" is 2 or more, "k" pieces of ns, ms, R^2s, R^3s, and R^4s) may be the same or different from each other; and the phrase "in the hydrocarbon group" refers to "inside the hydrocarbon group", "at terminals of the hydrocarbon group", or "within bonds of the hydrocarbon group"[[]]], and the following general formula (1),

General formula (1)



[[[In]] wherein, in the general formula (1): R^1 to R^{10} each represent hydrogen, or a saturated or unsaturated hydrocarbon group having 1 to 20 carbon atoms, wherein [[(]] an ether bond, an ester bond, or an alcoholic hydroxyl group may be included in the hydrocarbon group[[)]]; R^1 to R^{10} may each represent a residue derived by removing any one of R^1 to R^{10} from the structure represented by the general formula (1), or a residue derived by removing hydrogen from any one of R^1 to R^{10}; and the phrase "in the hydrocarbon group" refers to "inside the hydrocarbon group", "at terminals of the hydrocarbon group", or "within bonds of the hydrocarbon group"[[]]], a cationic polymerization initiator (i), and ~~optionally~~ a surfactant (e), wherein the surfactant (e) comprises a silicon-based surfactant (e1) having a dimethylsiloxane skeleton and/or a fluorine-based surfactant (e2) having hydrophobic groups of a hydrocarbon-based surfactant entirely or partially substituted with fluorine atoms.

4. – 6. (cancelled).

7. (withdrawn – currently amended) A cured product, which is obtained by heat curing the heat-curable resin composition according to any one of claims 1 to 3 and 11 to 15 [[6]].

8. (withdrawn) A cured product according to claim 7, which is used for an adhesive or an encapsulant.

9. (withdrawn) A cured product according to claim 7, wherein a warping by shrinkage in curing is 15 mm or less through a measurement method A, 6 mm or less through a measurement method B.

10. (withdrawn) A cured product according to claim 8, wherein a warping by shrinkage in curing is 15 mm or less through a measurement method A, 6 mm or less through a measurement method B.

11. (new) A heat-curable resin composition according to claim 2, wherein the content of the surfactant (e) is 0.05 to 5 parts by weight with respect to 100 parts by weight of the alicyclic epoxy compound (a) and the polyol (b) in total.

12. (new) A heat-curable resin composition according to claim 3, wherein the content of the surfactant (e) is 0.05 to 5 parts by weight with respect to 100 parts by weight of the alicyclic epoxy compound (a') in total.

13. (new) A heat-curable resin composition according to any one of claims 1, 2, and 11, wherein the surfactant (e) is a silicon-based surfactant (e1) having a dimethylsiloxane skeleton.

14. (new) A heat-curable resin composition according to claim 3 or 12, wherein the surfactant (e) is a silicon-based surfactant (e1) having a dimethylsiloxane skeleton.

15. (new) A heat-curable resin composition according to claim 3 or 12, wherein the surfactant (e) is a fluorine-based surfactant (e2) having hydrophobic groups of a hydrocarbon-based surfactant entirely or partially substituted with fluorine atoms.